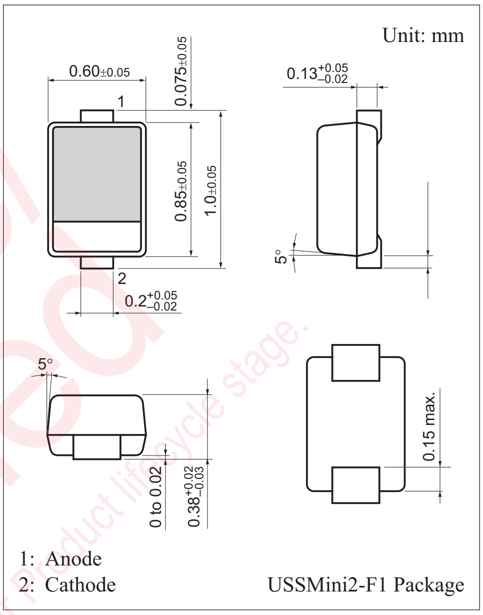
MAU2D29

Silicon epitaxial planar type

For high speed switching circuits



Marking Symbol: 1C

■ Features

- Optimum for high-density mounting
- Low forward voltage V_F
- Short reverse recovery time t_{rr}

■ Absolute Maximum Ratings $T_a = 25°C$

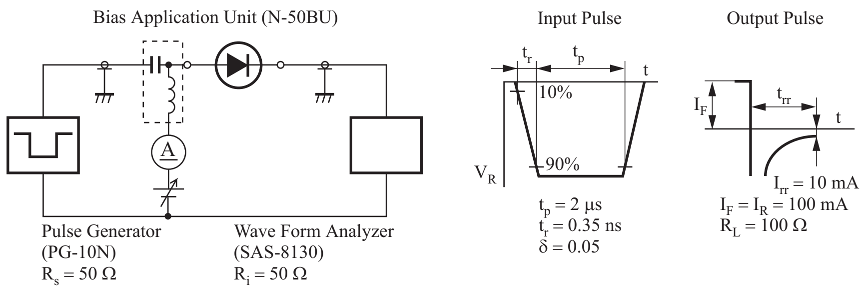
Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	30	V
Repetitive peak reverse voltage	V_{RRM}	30	V
Forward current	I_F	100	mA
Peak forward current	I_{FM}	200	mA
Non-repetitive peak forward surge current *	I_{FSM}	1	A
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	−55 to +125	°C

Note) *: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

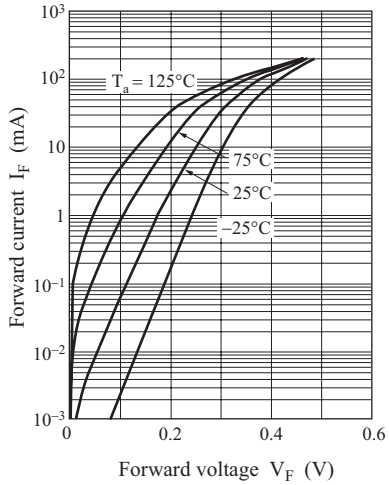
■ Electrical Characteristics $T_a = 25°C±3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_{F1}	$I_F = 10$ mA		0.25	0.29	V
	V_{F2}	$I_F = 100$ mA		0.39	0.42	V
Reverse current	I_{R1}	$V_R = 10$ V			25	μA
	I_{R2}	$V_R = 30$ V			120	μA
Terminal capacitance	C_t	$V_R = 0$ V, f = 1 MHz		11		pF
Reverse recovery time *	t_{rr}	$I_F = I_R = 100$ mA, $I_{rr} = 10$ mA, $R_L = 100\ \Omega$		1		ns

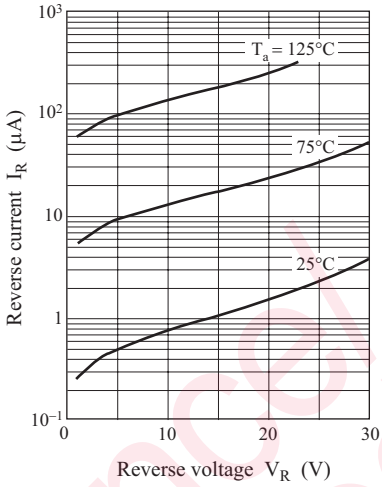
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. Absolute frequency of input and output is 250 MHz
4. *: t_{rr} measurement circuit



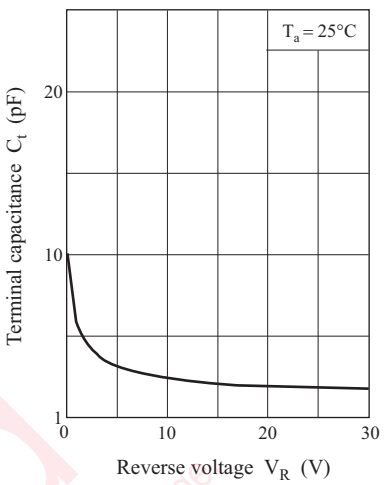
I_F — V_F



I_R — V_R



C_t — V_R



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(6) Comply with the instructions for use in order to prevent breakdown and characteristics change due to external factors (ESD, EOS, thermal stress and mechanical stress) at the time of handling, mounting or at customer's process. When using products for which damp-proof packing is required, satisfy the conditions, such as shelf life and the elapsed time since first opening the packages.

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